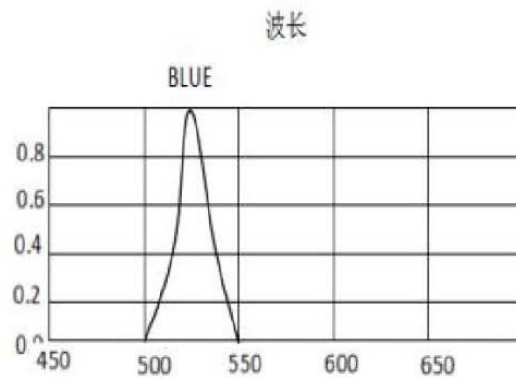
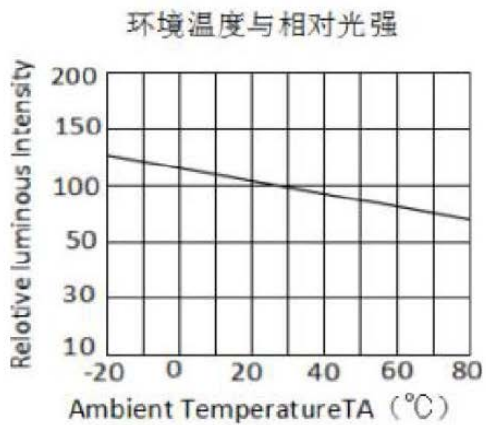
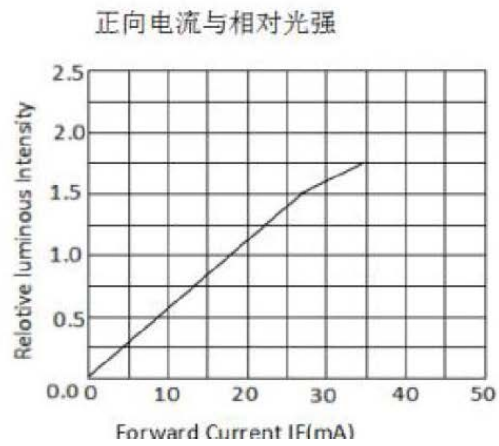
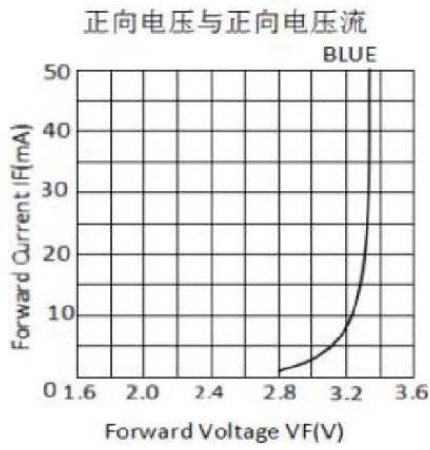
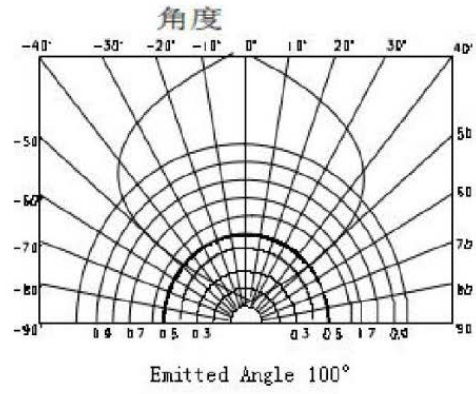
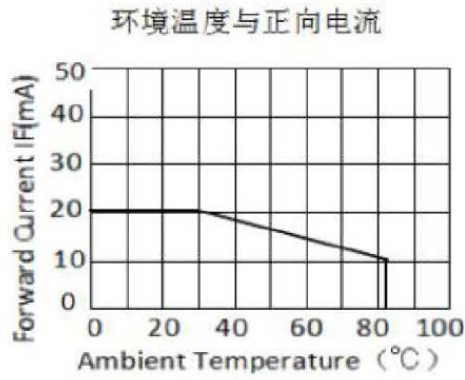
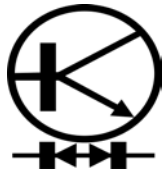


# YETDA INDUSTRY LTD.

Typical photo electricity characteristic curve chart





# YETDA INDUSTRY LTD.

## Precautions For Use :

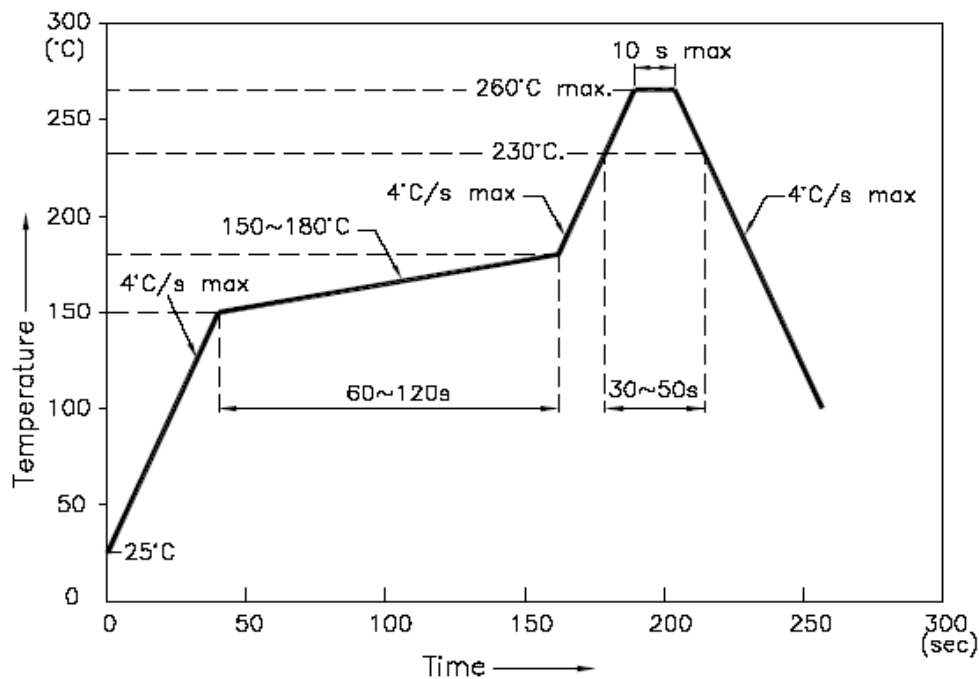
### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )

### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$  , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.

## ■ Reflow Temp/Time



## NOTES:

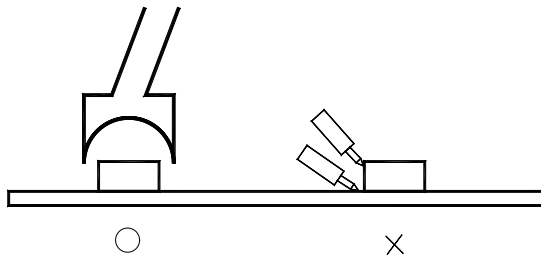
1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than  $20\text{W}$ , and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

■Rework

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.